

S/N: 09/832,884

FEB 26 2004

2/26/2004

DOCKET NO.: L/M-102-DIV

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Serial No.: 09/832,884
Divisional of 09/321,565

Confirmation No.: 2718

Applicant: Steve M. Danziger, et al.

Art Unit: 2829

Filed: April 12, 2001

Examiner: Evan T. Pert

Docket No: L/M-102-DIV

Customer No: 28892

For: Method and Apparatus for Evaluating a Known Good Die Using
Both Wire Bond and Flip-Chip Interconnects**TRANSMITTAL**US Patent & Trademark Office
2011 South Clark Place
Customer Window, Mail Stop: Non Fee Amendment
Crystal Plaza Two, Lobby, Room 1B03
Arlington, VA 22202

Sir: TRANSMITTED HEREWITH IS

 A RESPONSE, AN AMENDMENT, AN AMENDMENT AFTER FINAL,

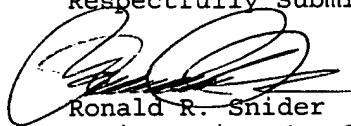
IN THE ABOVE-IDENTIFIED APPLICATION.

 Small entity status of this application under 37 CFR §1.9(f) is established
by a verified statement under 37 CFR §1.27 previously submitted.
 submitted herewith. No additional fee is required, as shown below.

CLAIMS PENDING AFTER AMENDMENT		CLAIMS PREVIOUSLY PAID		NEW CLAIMS EXTRA	ADDITIONAL FEES			
					SMALL ENTITY		OTHER THAN SMALL ENTITY	
TOTAL	5	MINUS	20	= 0	x\$9= 0.00		x\$18= 0.00	
INDEP	1	MINUS	3	= 0	x43= 0.00		x\$86= 0.00	
NEW MULTIPLE DEPENDENT CLAIMS				0	x\$145= 0.00		x\$290= 0.00	
AND CLAIMS DEPENDENT THEREON				0	x\$145= 0.00		x\$290= 0.00	
TOTAL ADDITIONAL FEE					0.00		0.00	

This amount is believed to be correct, however, the Commissioner is hereby authorized to charge any deficiency or credit any overpayment to Deposit Account No. 19-2816. This authorization applies to both filing fees under 37 CFR §1.16 and processing fees (such as extension of time) under 37 CFR §1.17. A duplicate copy of this transmittal is attached.

Respectfully Submitted,



Ronald R. Snider
Registration No. 24,962

Date: February 26, 2004

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AMENDMENT

US Patent & Trademark Office
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Arlington, VA 22202

Sir:

In response to the Office Action of February 10, 2004, please
amend the above-identified application as follows:

Amendments to the Claims are reflected in the listing of
claims which begins on page 2 of this paper.

Remarks begin on page 4 of this paper.